

# RF Q2™ SERIES QMS-RF, QFS-RF SERIES

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?QMS-RF](http://www.samtec.com?QMS-RF) or [www.samtec.com?QFS-RF](http://www.samtec.com?QFS-RF)

### Insulator Material:

Liquid Crystal Polymer



### Contact, Terminal & Ground Plane Material:

Phosphor Bronze

### Plating:

Au over 50µ" (1,27µm) Ni

(Tin on Ground Plane Tail)

### Current Rating:

Contact: 1.5A @ 30°C

Temperature Rise

Ground Plane: 7.2A @ 30°C

Temperature Rise

### Voltage Rating:

300 VAC

### Operating Temp:

-55°C to +125°C

### RoHS Compliant:

Yes

### Processing:

#### Max Processing Temp:

230°C for 60 seconds, or

260°C for 20 seconds 3x

#### Lead-Free Solderable:

Yes

#### SMT Lead Coplanarity:

(0,10mm) .004" max (026-078)

#### Board Stacking:

For applications requiring more

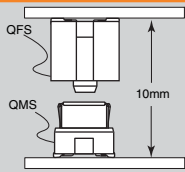
than two connectors per board,

contact [ipg@samtec.com](mailto:ipg@samtec.com)

## APPLICATION SPECIFIC OPTION

- Differential Pairs
- Call Samtec.

## APPLICATION



**Note:** Some lengths, styles and options are non-standard, non-returnable.

**QMS**

**NO. OF PINS PER ROW**

**05.75**

**PLATING OPTION**

**D**

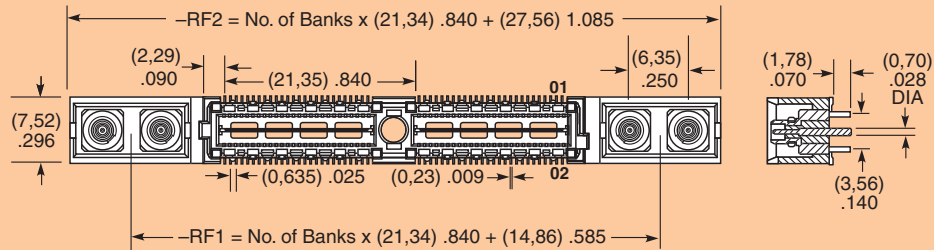
**END OPTION**

Mates with:  
QFS-RF

**-026, -052, -078**  
(52 total pins per bank)

**-L**  
= 10µ" (0,25µm) Gold on Signal Pins,  
and Ground Plane  
(Gold flash on Signal Pin tails,  
Tin on Ground Plane tails)

**-RF1**  
= 1 RF  
Plug per End  
**-RF2**  
= 2 RF  
Plugs per End



**QFS**

**NO. OF PINS PER ROW**

**04.25**

**PLATING OPTION**

**D**

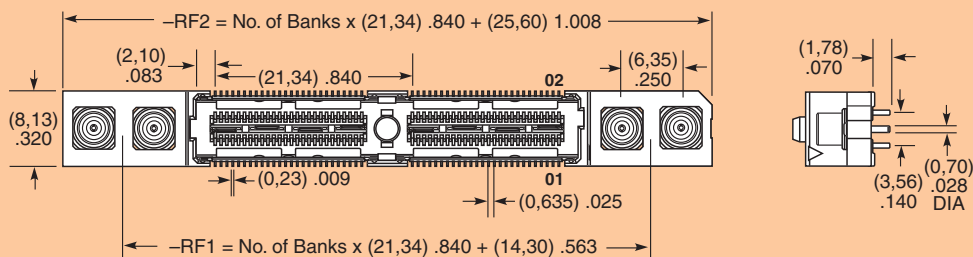
**END OPTION**

Mates with:  
QMS-RF

**-026, -052, -078**  
(52 total pins per bank)

**-L**  
= 10µ" (0,25µm) Gold on Signal Pins,  
and Ground Plane  
(Gold flash on Signal Pin tails,  
Tin on Ground Plane tails)

**-RF1**  
= 1 RF  
Jack per End  
**-RF2**  
= 2 RF  
Jacks per End



Due to technical progress, all designs, specifications and components are subject to change without notice.

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